



200G QSFP56 SR4 Transceiver

**Hot Pluggable, MPO / MTP, 850nm VCSEL, OM3 70M / OM4 100M,
OIF-CMIS Management & DDM**

Part Number: FQ56-S9-M85-X1D-CD1



Overview

FQ56-S9-M85-X1D-CD1 is a parallel fiber optical transceiver module for 212.5Gbps data transmission applications at 850nm. It is ideally suited for datacom & storage area network (SAN/NAS) applications based on IEEE 802.3cd 200GBASE-SR4 standard. Designed for short range multi-lane data communication, the QSFP56 full-duplex optical module with MPO-12 APC receptacle integrates four independent transmitter and receiver channels each capable 53.125Gbps operation for an aggregate data rate of 212.5Gbps up to MMF OM3 70m / OM4 100m optical links.

Applications

- 200GBASE-SR4 Ethernet @212.5G
- Breakout to 4 x 50GBASE-SR Ethernet
- Data Centers Switch Interconnect
- Server and Storage Area Network Interconnect

Features

- Compliant with IEEE802.3cd 200GBASE-SR4
- Compliant with SFF-8665 QSFP56 MSA
- Compliant with IEEE 802.3bs CAUI-4 Interface
- 4 independent full-duplex channels
- Optical Data Rate PAM4 26.5625GBd per Lane
- Electrical Data Rate PAM4 26.5625GBd per Lane
- Built in quad Tx CDR and Rx CDR
- Hot Pluggable QSFP56 footprint
- 4CH 850nm VCSEL array transmitter
- 4CH PIN array receiver
- MPO-12 APC receptacle connector
- 2-wire interface for management and diagnostic monitor compliant with OIF-CMIS
- Single 3.3V power supply
- Link distance 70m over OM3 fiber and 100m over OM4 fiber
- Maximum power consumption 5W
- RoHS compliant



Laser Safety

- This is a Class 1 Laser Product complies with 21 CFR 1040.10 and 1040.11 except for conformance with IEC 60825-1 Ed. 3., as described in Laser Notice No. 56, dated May 8, 2019.
- Caution: Use of control or adjustments or performance of procedure other than those specified herein may result in hazardous radiation exposure.

Absolute Maximum Ratings

Parameters	Symbol	Min.	Max.	Unit
Storage Temperature	T _{ST}	-40	+85	°C
Storage Relative Humidity	RH	0	85	%
Supply Voltage	V _{CC3}	-0.5	+3.6	V

Recommended Operating Conditions

Parameters	Symbol	Min.	Typ.	Max.	Unit
Case Operating Temperature	T _{OP}	0	-	+70	°C
Supply Voltage	V _{CC}	+3.13	+3.3	+3.47	V
Data Rate, per Lane (PAM4)	DR		26.5625		GBd
Data Rate Accuracy	ΔDR	-100		+100	ppm
Bit Error Rate (Pre-FEC)	BER			2.4x10 ⁻⁴	
Bit Error Rate (Post-FEC)	BER			1x10 ⁻¹²	
Supply Current (+3.3V)	I _{CC}			1800	mA
Power Consumption	P			6	W
Transceiver Power-on Initialization Time				2000	ms
Control Input Voltage High	V _{IH}	2.0		V _{CC}	V
Control Input Voltage Low	V _{IL}	GND		0.8	V
Control Output Voltage High	V _{OH}	2.0		V _{CC}	V
Control Output Voltage Low	V _{OL}	GND		0.8	V



Transmitter Electro-optical Characteristics

V_{CC} = 3.13V to 3.47V, T_{OP} = 0 °C to 70 °C

Parameters	Symbol	Min.	Typ.	Max.	Unit	Note
Optical Data Rate, per Lane	DR _{OP}		26.5625		GBd	PAM4
Optical Wavelength, each Lane	λ_c	840	850	860	nm	
Spectral Width (RMS) (Modulated)	$\Delta\lambda$			0.6	nm	
Average Launch Power, per Lane	P _{AVG}	-6.5		+4	dBm	1
Outer Optical Modulation Amplitude (OMA _{Outer}), per Lane	P _{OMA}	-4.5		+3	dBm	2
Launch Power in OMA _{Outer} minus TDECQ, per Lane	OMA-TDECQ	-5.9			dB	
Transmitter and Dispersion Eye Clouser for PAM4, per Lane	TEQCQ			4.5	dB	3
Optical Extinction Ratio	ER	3			dB	
Average Launch Power OFF, per Lane	P _{OFF}			-30	dBm	
Optical Return Loss Tolerance	ORLT			12	dB	
Encircled Flux		$\geq 86\%$ at 19 μm $\leq 30\%$ at 4.5 μm				4
Electrical Data Rate, per Lane (TP1)	D _{REL}		26.5625		GBd	PAM4
Differential Data Input Voltage (TP1a)	V _{IN-PP}	900			mVpp	5
Differential Termination Mismatch (TP1)				10	%	
Single-ended Voltage Tolerance Range (Min) (TP1a)		-0.4		3.3	V	
DC Common Mode Input Voltage (TP1)	CMV _{IN}	-350		2850	mV	6

Note1: Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.

Note2: Even if the TDECQ < 1dB, the OMA_{Outer} (min) must exceed the minimum value specified here.

Note3: TDECQ is specified and measured as per IEEE802.3.cm Clause 150.8.5.

Note4: If measured into type A1a.2, or type A1a.3, or type A1a.4, 50 μm fibers in accordance with IEC 61280-1-4.

Note5: With the exception to IEEE 802.3bs 120E.3.1.2 that the pattern is PRBS31Q or scrambled idle.

Note6: DC common mode voltage generated by the host. Specification includes effects of ground offset voltage.



Receiver Electro-optical Characteristics

V_{CC} = 3.13V to 3.47V, T_{OP} = 0 °C to 70 °C

Parameters	Symbol	Min.	Typ.	Max.	Unit	Note
Optical Data Rate, per Lane	DR _{OP}		26.5625		GBd	PAM4
Optical Wavelength, each Lane	λ _C	840	850	860	nm	
Damage Threshold, per Lane	D _{TH}	+5			dBm	1
Average Receive Power, per Lane	PRX-AVG	-8.4		+4	dBm	2
Receive Power (OMA _{Outer}), per Lane	PRX-OMA			+3	dBm	
Receive Sensitivity (OMA _{Outer}), per Lane	SEN _{OMA}	Max (-6.5, SECQ-7.9)			dBm	3
Stressed Receiver Sensitivity (OMA _{Outer}), per Lane	SRS _{OMA}			-3.4	dBm	4
Receiver Reflectance	R _{RX}			-12	dB	
LOS De-Assert	LOS _D			-9	dBm	
LOS Assert	LOS _A	-30		-10	dBm	
LOS Hysteresis	LOS _{HY}	0.5			dB	
Electrical Data Rate, per Lane (TP4)	DR _{EL}		26.5625		GBd	PAM4
Differential Data Output Voltage (TP4)	V _{OUT-PP}			900	mVpp	
AC Common Mode Output Voltage, RMS (TP4)				17.5	mV	
Differential Termination Mismatch (TP4)				10	%	
Transition Time, 20% to 80% (TP4)		9.5			ps	
Near-end Eye Symmetry Mask Width (ESMW) (TP4)		0.265			UI	
Near-end Eye Height, Differential (TP4)		70			mV	
Far-end Eye Symmetry Mask Width (ESMW) (TP4)			0.2		UI	
Far end Eye Height, Differential (TP4)		30			mV	
Far-end Pre-cursor ISI Ratio (TP4)		-4.5		2.5	%	
DC Common Mode Output Voltage (TP4)	CMV _{OUT}	-350		2850	mV	5

Note1: The receiver shall be able to tolerate, without damage, continuous exposure to a modulated optical input signal having this power level on one lane. The receiver does not have to operate correctly at this input power.

Note2: Average receive power, per lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.

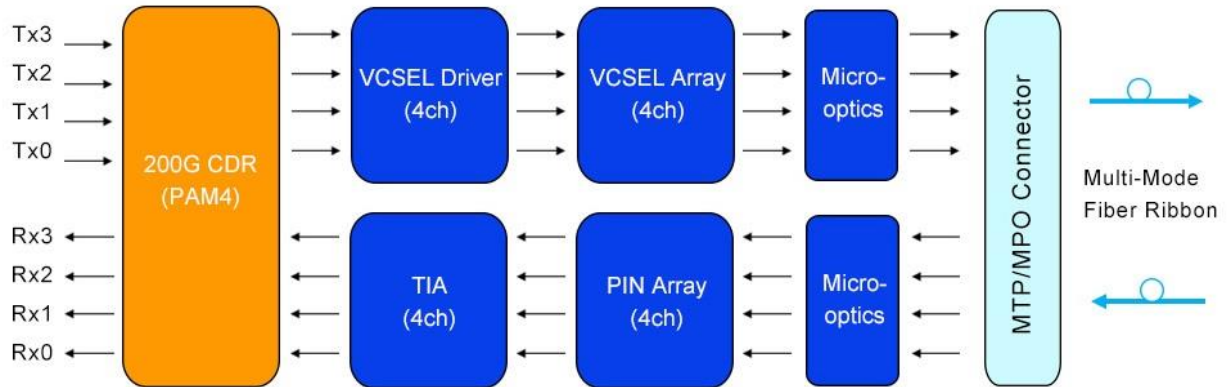
Note3: Receiver sensitivity is informative and is defined for a transmitter with a value of SECQ up to 4.5dB.

Note4: Measured with conformance test signal at receiver input for the BER of 2.4x10⁻⁴.

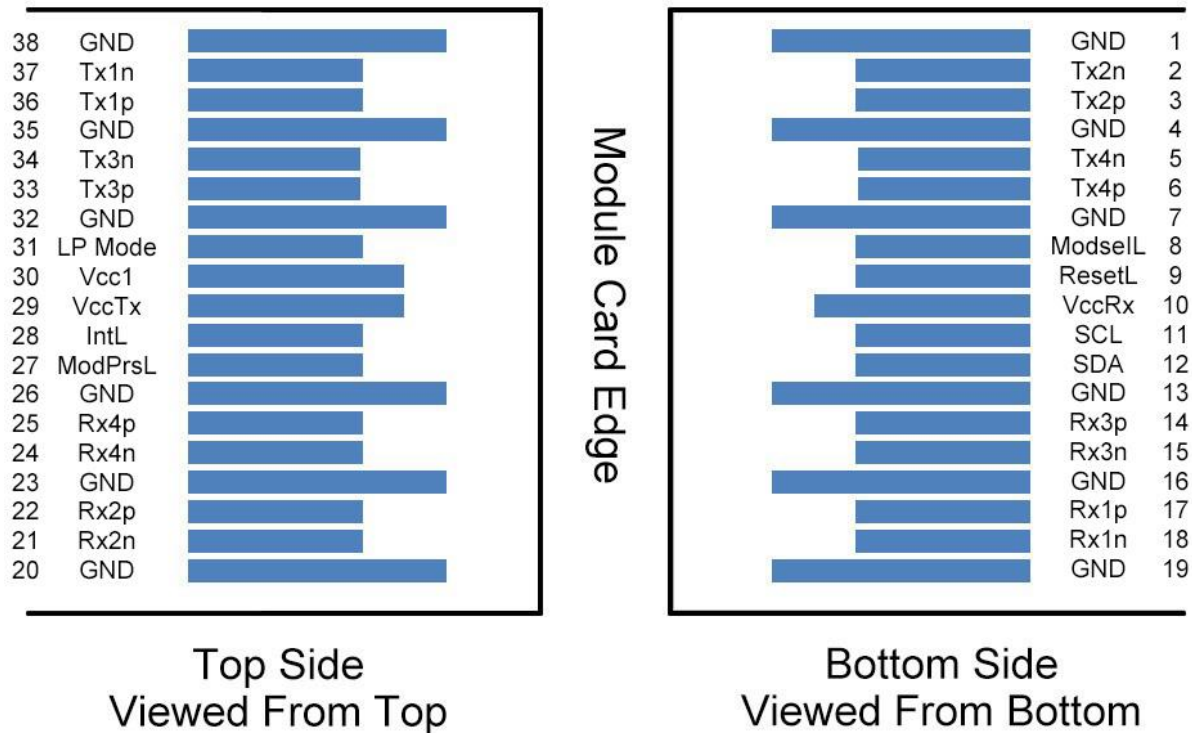
Note5: DC common mode voltage generated by the host. Specification includes effects of ground offset voltage.



Transceiver Block Diagram



Pin Assignment





Pin Description

Pin	Logic	Name	Function / Description
1		GND	Module Ground
2	CML-I	Tx2n	Transmitter Inverted Data Input
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input
4		GND	Module Ground
5	CML-I	Tx4n	Transmitter Inverted Data Input
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input
7		GND	Module Ground
8	LVTLL-I	ModSelL	Module Select
9	LVTLL-I	ResetL	Module Reset
10		VccRx	+3.3V Power Supply Receiver
11	LVC MOS-I/O	SCL	2-Wire Serial Interface Clock
12	LVC MOS-I/O	SDA	2-Wire Serial Interface Data
13		GND	Module Ground
14	CML-O	Rx3p	Receiver Non-Inverted Data Output
15	CML-O	Rx3n	Receiver Inverted Data Output
16		GND	Module Ground
17	CML-O	Rx1p	Receiver Non-Inverted Data Output
18	CML-O	Rx1n	Receiver Inverted Data Output
19		GND	Module Ground
20		GND	Module Ground
21	CML-O	Rx2n	Receiver Inverted Data Output
22	CML-O	Rx2p	Receiver Non-Inverted Data Output
23		GND	Module Ground
24	CML-O	Rx4n	Receiver Inverted Data Output
25	CML-O	Rx4p	Receiver Non-Inverted Data Output
26		GND	Module Ground
27	LVTLL-O	ModPrsL	Module Present
28	LVTLL-O	IntL	Interrupt
29		VccTx	+3.3V Power Supply Transmitter
30		Vcc1	+3.3V Power Supply
31	LVTLL-I	LPMODE	Low Power Mode
32		GND	Module Ground

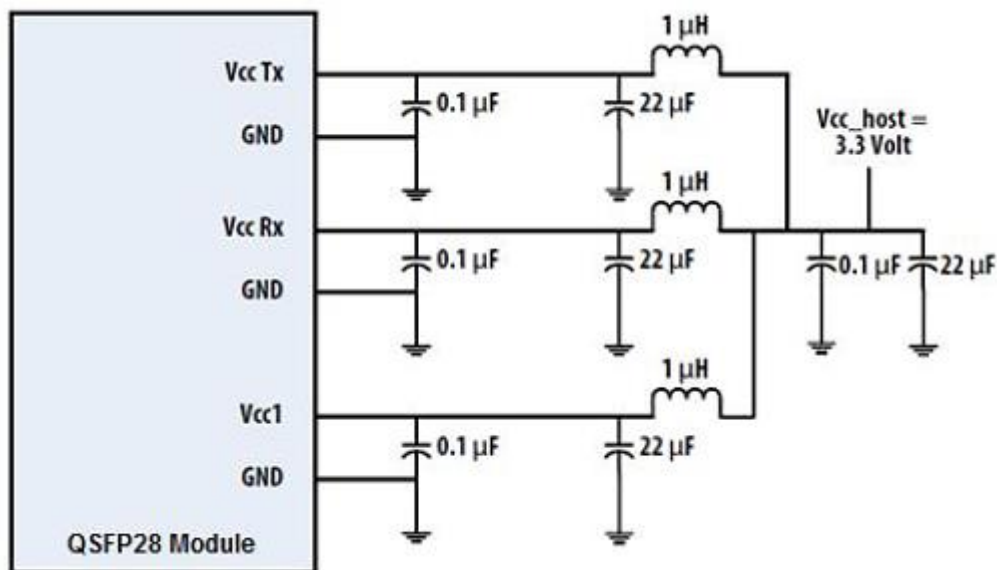


33	CML-I	Tx3p	Transmitter Non-Inverted Data Input
34	CML-I	Tx3n	Transmitter Inverted Data Input
35		GND	Module Ground
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input
37	CML-I	Tx1n	Transmitter Inverted Data Input
38		GND	Module Ground

Note1: GND is the symbol for signal and supply (power) common for QSFP56 modules. All are common within the QSFP56 module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground lane.

Note2: VccRx, Vcc1 and VccTx are the receiver and transmitter power suppliers and shall be applied concurrently. Recommended host board power supply filtering is shown below. Vcc Rx, Vcc1 and Vcc Tx may be internally connected within the QSFP56 transceiver module in any combination. The connector pins are each rated for a maximum current of 1000mA.

Recommended Power Supply Filter





Digital Diagnostic Functions

As defined by the QSFP56 MSA, Ficer's QSFP56 transceivers provide digital diagnostic functions via a 2-wire serial interface, which allows real-time access to the following operating parameters:

- Transceiver temperature
- Laser bias current (4-Channel)
- Transmitted optical power (4-Channel)
- Received optical power (4-Channel)
- Transceiver supply voltage

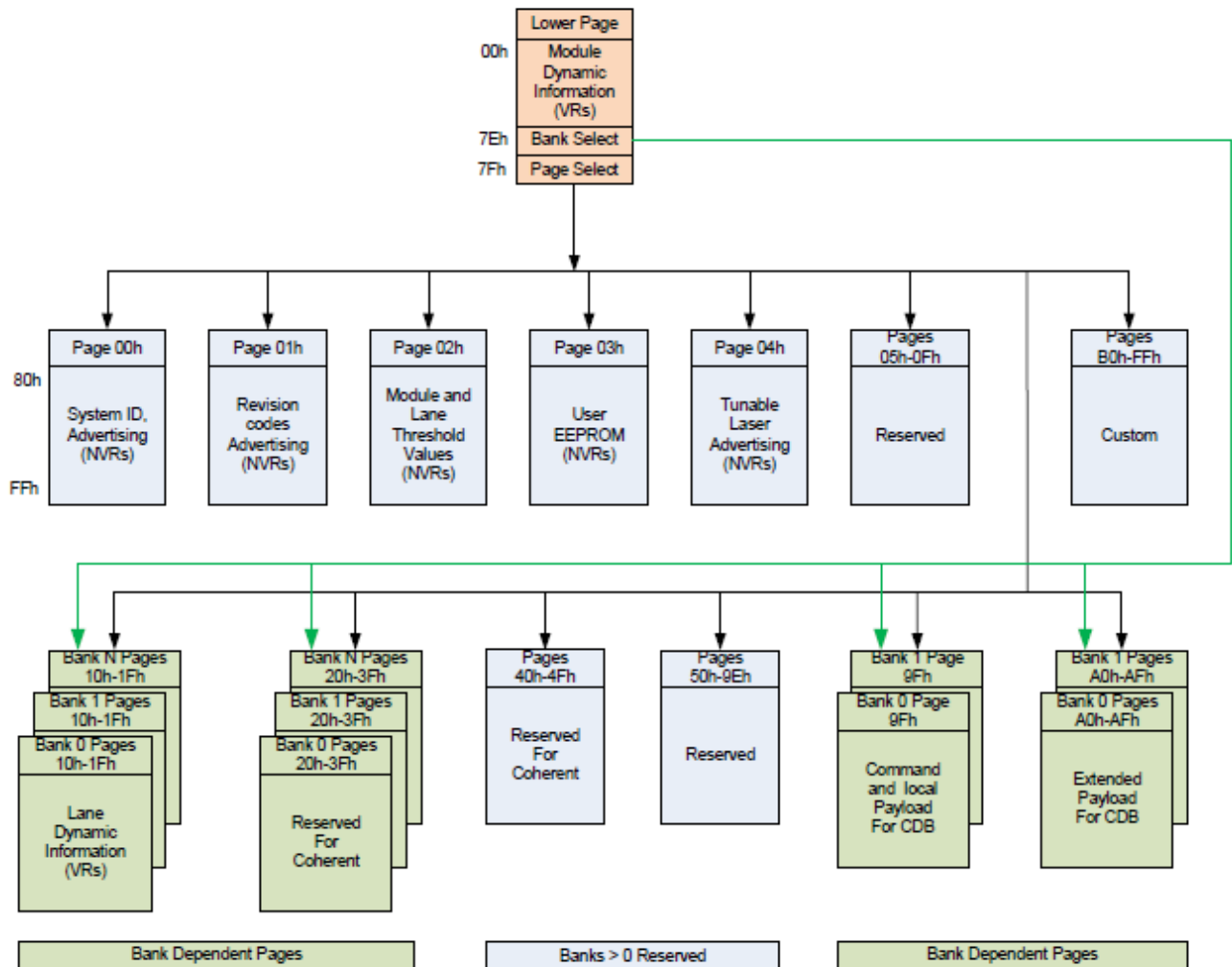
It also provides a sophisticated system of alarm and warning flags, which may be used to alert end-users when particular operating parameters are outside of a factory-set normal range.

The operating and diagnostics information is monitored and reported by a Digital Diagnostics Controller (DDC) inside the transceiver, which is accessed through the 2-wire serial interface. When the serial protocol is activated, the serial clock signal (SCL pin) is generated by the host. The positive edge clocks data into the QSFP56 transceiver into those segments of its memory map that are not write-protected. The negative edge clocks data from the QSFP56 transceiver. The serial data signal (SDA pin) is bi-directional for serial data transfer. The host uses SDA in conjunction with SCL to mark the start and end of serial protocol activation. The memories are organized as a series of 8-bit data words that can be addressed individually or sequentially. The 2-wire serial interface provides sequential or random access to the 8 bit parameters, addressed from 000h to the maximum address of the memory.

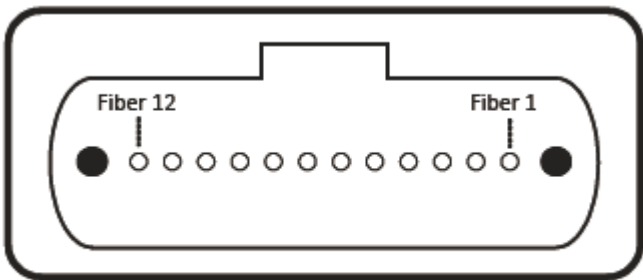
For more detailed information including memory map definitions, please see the QSFP56 MSA Specification.



Digital Diagnostic Memory Map (CMIS)



Optical Interface Lanes and Assignment



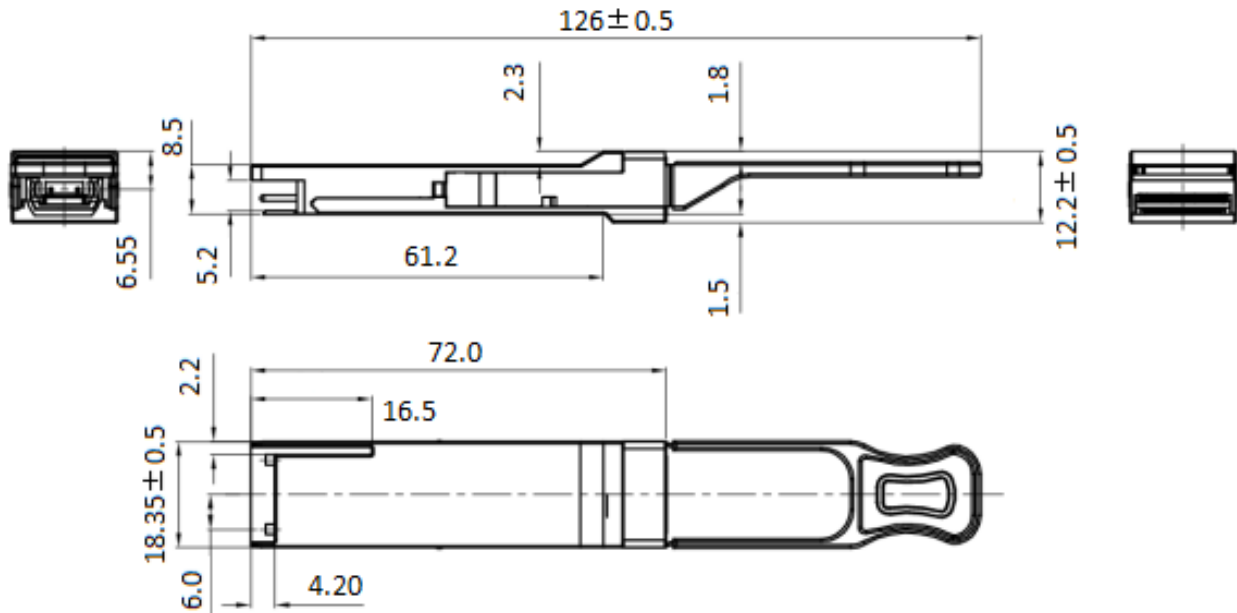
Outside View of the QSFP56 Module MPO-12

Fiber #	Lane Assignment
1	Rx0
2	Rx1
3	Rx2
4	Rx3
5,6,7,8	Not used
9	Tx3
10	Tx2
11	Tx1
12	Tx0

lane assignment



Mechanical Dimensions



(All Dimensions are ± 0.20 mm Unless Otherwise Specified, Unit: mm)

Ordering Information

Part No.	Tx	Rx	Link	DDM	Temp.
FQ56-S9-M85-X1D-CD1	850 nm	850 nm	MM OM3 70m MM OM4 100m	Yes	0~70°C

Note: Distances are indicative only. To calculate a more precise link budget based on specific conditions in your application, please refer to the optical characteristics.